

July 2015

# FSUSB42 — Low-Power, Two-Port, High-Speed, USB2.0 (480Mbps) UART Switch

### **Features**

- Low On Capacitance: 3.7 pF Typical
   Low On Resistance: 3.9 Ω Typical
- Low Power Consumption: 1 μA Maximum
  - 15 μA Maximum I<sub>CCT</sub> over an Expanded Voltage Range (V<sub>IN</sub>=1.8 V, V<sub>CC</sub>=4.4 V)
- Wide -3 db Bandwidth: > 720 MHz
- Packaged in:
  - 10-Lead UMLP (1.4 x 1.8 mm)
  - 10-Lead MSOP
- 8 kV ESD Rating, >16 kV Power / GND ESD Rating
- Over-Voltage Tolerance (OVT) on all USB Ports Up to 5.25 V without External Components

# **Applications**

- Cell phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

# **Description**

The FSUSB42 is a bi-directional, low-power, two-port, high-speed, USB2.0 switch. Configured as a double-pole, double-throw switch (DPDT) switch, it is optimized for switching between any combination of high-speed (480 Mbps) or Full-Speed (12 Mbps) sources.

The FSUSB42 is compatible with the requirements of USB2.0 and features an extremely low on capacitance ( $C_{ON}$ ) of 3.7 pF. The wide bandwidth of this device (720 MHz) exceeds the bandwidth needed to pass the third harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

The FSUSB42 contains special circuitry on the switch I/O pins for applications where the  $V_{CC}$  supply is powered-off ( $V_{CC}$ =0 V), which allows the device to withstand an over-voltage condition. This device is designed to minimize current consumption even when the control voltage applied to the SEL pin is lower than the supply voltage ( $V_{CC}$ ). This feature is especially valuable to ultra-portable applications, such as cell phones, allowing for direct interface with the general-purpose I/Os of the baseband processor. Other applications include switching and connector sharing in portable cell phones, PDAs, digital cameras, printers, and notebook computers.

# **Ordering Information**

Part Number	rt Number Top Mark Operating Temperature Range		Package
FSUSB42UMX	HE	-40 to +85°C	10-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 1.4 x 1.8 mm
FSUSB42MUX	FSUSB42	-40 to +85°C	10-Lead, Molded Small-Outline Package (MSOP) JEDEC MO-187, 3.0 mm Wide

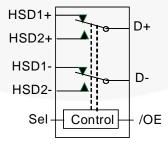
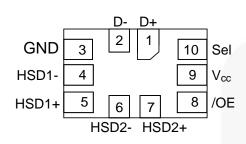


Figure 1. Analog Symbol

# **Pin Assignments**



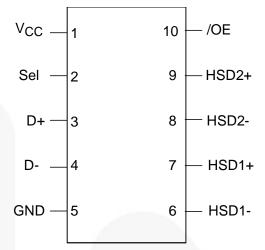


Figure 2. 10-Lead UMLP (Top-Through View)

Figure 3. 10-Lead MSOP (Top-Through View)

# **Pin Definitions**

UMLP Pin#	MSOP Pin#	Name	Description	
1	3	D+	Common USB Data Bus	
2	4	D-	Common USB Data Bus	
3	5	GND	Ground	
4	6	HSD1-	Multiplexed Source Input 1	
5	7	HSD1+	Multiplexed Source Input 1	
6	8	HSD2-	HSD2- Multiplexed Source Input 2	
7	9	HSD2+	Multiplexed Source Input 2	
8	10	/OE	Switch Enable	
9	1	V <sub>CC</sub>	Supply Voltage	
10	2	Sel	Switch Select	

# **Truth Table**

SEL	/OE	Function
X	HIGH	Disconnect
LOW	LOW	D+= HSD1+, D-= HSD1-
HIGH	LOW	D+= HSD2+, D-= HSD2-

#### Notes:

- LOW ≤V<sub>IL</sub>.
- 2. HIGH ≥V<sub>IH</sub>.
- 3. X=Don't Care.

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
Vcc	Supply Voltage	Supply Voltage		5.6	V
V <sub>CNTRL</sub>	DC Input Voltage (S, /OE) <sup>(4)</sup>		-0.5	V <sub>CC</sub>	V
V <sub>SW</sub>	DC Switch I/O Voltage <sup>(4)</sup> (VCC=0V)	10	-0.50	5.25	V
I <sub>IK</sub>	DC Input Diode Current		-50		mA
l <sub>out</sub>	DC Output Current			100	mA
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
MSL	Moisture Sensitivity Level (JEDEC J-STD-020	)A)		1	Level
9	\	All Pins	7		
//	Lhoman Barks Market JEDEO, JEODOO A444	I/O to GND	8		
	Human Body Model, JEDEC: JESD22-A114	Power to GND	16		
ESD		D+/D-	9		kV
	IEC 61000-4-2 System on USB Connector	Air Discharge	15		A
	Pins D+ & D-	Contact	8		
	Charged Device Model, JEDEC: JESD22-C10	)1	2		

#### Note:

4. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	2.4	4.4	V
V <sub>CNTRL</sub>	Control Input Voltage (S, /OE) <sup>(5)</sup>	0	V <sub>CC</sub>	V
V <sub>SW</sub>	Switch I/O Voltage	-0.5	4.5	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

## Note:

5. The control input must be held HIGH or LOW and it must not float.

# **DC Electrical Characteristics**

All typical value are at T<sub>A</sub>=25°C unless otherwise specified.

Comple at	Davamatar	Condition	V 00	T <sub>A</sub> =- 40°C to +85°C			l lo:4
Symbol	Parameter	Condition	V <sub>CC</sub> (V)	Min.	Тур.	Max.	Unit
V <sub>IK</sub>	Clamp Diode Voltage	I <sub>IN</sub> =-18mA	3.0			-1.2	V
V	Input Voltage High		2.4 to 3.6	1.3			V
V <sub>IH</sub>	Input Voltage High		4.3	1.7			V
V <sub>IL</sub>	Input Voltage Low		2.4 to 3.6			0.5	V
VIL	input voltage Low		4.3			0.7	V
I <sub>IN</sub>	Control Input Leakage	V <sub>SW</sub> =0 to V <sub>CC</sub>	0 to 4.3	-1		1	μΑ
I <sub>OZ</sub>	Off State Leakage	$0 \le Dn$ , HSD1n, HSD2n $\le 3.6 \text{ V}$	4.3	-2		2	μΑ
l <sub>OFF</sub>	Power-Off Leakage Current (All I/O Ports)	V <sub>SW</sub> =0 V to 4.3 V, V <sub>CC</sub> =0 V Figure 5	0	-2		2	μΑ
6	HS Switch On Resistance <sup>(6)</sup>	V <sub>SW</sub> =0.4 V, I <sub>ON</sub> =-8 mA	2.4		4.5	7.5	0
R <sub>ON</sub>	ns switch on Resistance	Figure 4	3.0		3.9	6.5	Ω
$\Delta R_{ON}$	HS Delta R <sub>ON</sub> <sup>(7)</sup>	V <sub>SW</sub> =0.4 V, I <sub>ON</sub> =-8 mA	3.0		0.65		Ω
Icc	Quiescent Supply Current	V <sub>CNTRL</sub> =0 or V <sub>CC</sub> , I <sub>OUT</sub> =0	4.3			1	μΑ
laan	Increase in I <sub>CC</sub> Current per	V <sub>CNTRL</sub> =2.6 V, V <sub>CC</sub> =4.3 V	4.3			10	μΑ
Ісст	Control Voltage and V <sub>CC</sub>	V <sub>CNTRL</sub> =1.8 V, V <sub>CC</sub> =4.3 V	4.3		Ų	15	μΑ

# Notes:

- 6. Measured by the voltage drop between HSDn and Dn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSDn or Dn ports).
- 7. Guaranteed by characterization.

# **AC Electrical Characteristics**

All typical value are for  $V_{CC}$ =3.3 V at  $T_A$ =25°C unless otherwise specified.

Cumbal	Doromotor	Condition	V 00	T <sub>A</sub> =- 40°C to +85°C			Unit
Symbol	Parameter	Condition	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Unit
	Turn-On Time	$R_L$ =50 Ω, $C_L$ =5 pF, $V_{SW}$ =0.8 V,	2.4		24	40	200
t <sub>ON</sub>	S, /OE to Output	Figure 6, Figure 7	3.0 to 3.6		13	30	ns
+	Turn-Off Time	$R_L=50 \Omega$ , $C_L=5 pF$ , $V_{SW}=0.8 V$ ,	2.4		15	35	nc
t <sub>OFF</sub>	S, /OE to Output		3.0 to 3.6		12	25	ns
t <sub>PD</sub>	Propagation Delay <sup>8</sup>	$C_L$ =5 pF, $R_L$ =50 $\Omega$ , Figure 6, Figure 8	3.3		0.25		ns
	Break-Before-Make	R <sub>L</sub> =50 Ω, C <sub>L</sub> =5 pF,	2.4	2.0		10	
t <sub>BBM</sub>	break-belore-wake	V <sub>SW1</sub> =V <sub>SW2</sub> =0.8 V, Figure 10	3.0 to 3.6	2.0		6.5	ns
O <sub>IRR</sub>	Off Isolation	$R_L$ =50 $\Omega$ , f=240 MHz, Figure 12	3.0 to 3.6		-30		dB
Xtalk	Non-Adjacent Channel Crosstalk	$R_L$ =50 Ω, f=240 MHz, Figure 13	3.0 to 3.6		-45		dB
BW	DM Oally Demokrately	$R_L=50 \Omega$ , $C_L=0$ pF, Figure 11	2 0 to 2 6		720		MHz
DVV	-3db Bandwidth	$R_L=50 \Omega$ , $C_L=5 pF$ , Figure 11	3.0 to 3.6		550		MHz

#### Note:

8. Guaranteed by characterization.

# **USB High-Speed-Related AC Electrical Characteristics**

All typical value are for V<sub>CC</sub>=3.3 V at T<sub>A</sub>=25°C unless otherwise specified.

Symbol	Parameter	Condition	V (V)	T <sub>A</sub> =- 40°C to +85°C			Unit
Symbol	Parameter	Condition	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Onit
t <sub>SK(P)</sub>	Skew of Opposite Transitions of the Same Output <sup>(9)</sup>	$C_L=5$ pF, $R_L=50$ $\Omega$ , Figure 9		Λ	20		ps
tJ	Total Jitter <sup>(9)</sup>	R <sub>L</sub> =50 $\Omega$ , C <sub>L</sub> =5 pF, t <sub>R</sub> =t <sub>F</sub> =500 ps (10-90%) at 480 Mbps (PRBS=2 <sup>15</sup> – 1)			200		ps

#### Note:

9. Guaranteed by characterization.

# Capacitance

Sumbol Baramatar		ool Parameter Condition	T <sub>A</sub> =- 40°C to +85°C			l lni4
Symbol	raiailletei	Condition	Min.	Тур.	Max.	Unit
C <sub>IN</sub>	Control Pin Input Capacitance	V <sub>CC</sub> =0 V		1.5		
C <sub>ON</sub>	D+/D- On Capacitance	V <sub>CC</sub> =3.3 V, /OE=0 V, f=240 MHz, Figure 15		3.7		рF
C <sub>OFF</sub>	D1n, D2n Off Capacitance	V <sub>CC</sub> and /OE=3.3 V, Figure 14		2.0		

# **Test Diagrams**

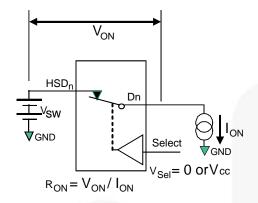
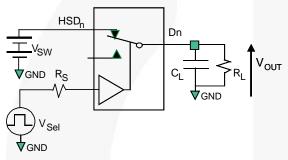
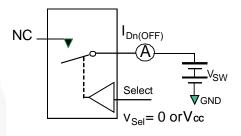


Figure 4. On Resistance



 $R_L$ ,  $R_S$ , and  $C_L$  are functions of the application environment (see AC Tables for specific values)  $C_L$  includes test fixture and stray capacitance.

Figure 6. AC Test Circuit Load



\*\*Each switch port is tested separately

Figure 5. Off Leakage

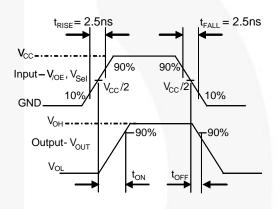


Figure 7. Turn-On / Turn-Off Waveforms

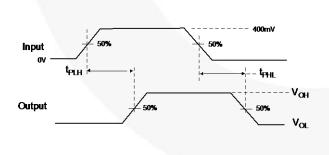


Figure 8. Propagation Delay (t<sub>R</sub>t<sub>F</sub> - 500 ps)

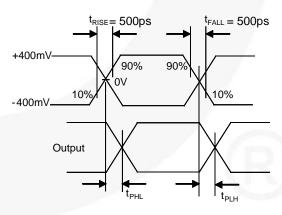


Figure 9. Intra-Pair Skew Test t<sub>SK(P)</sub>

# HSD<sub>n</sub> Nout Nout

Figure 10. Break-Before-Make Interval Timing

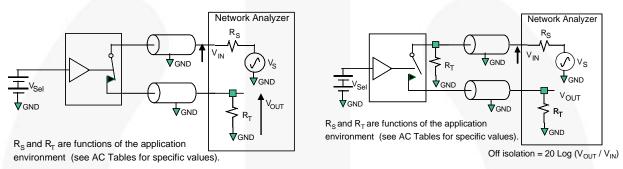


Figure 11. Bandwidth

Test Diagrams (Continued)

Figure 12. Channel Off Isolation

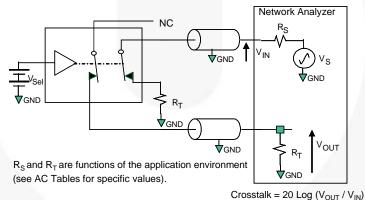


Figure 13. Non-Adjacent Channel-to-Channel Crosstalk

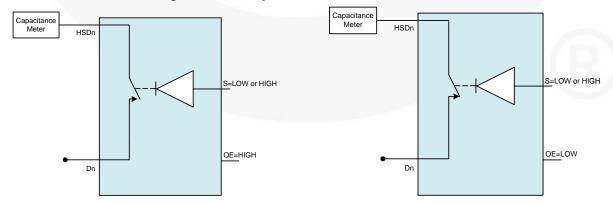
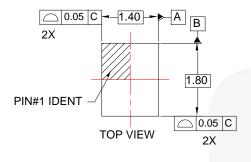
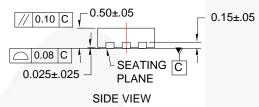


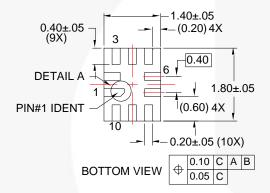
Figure 14. Channel Off Capacitance

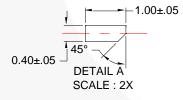
Figure 15. Channel On Capacitance

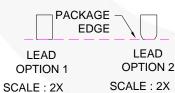
# **Physical Dimensions**

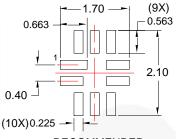




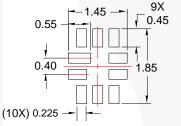








# RECOMMENDED LAND PATTERN



OPTIONAL MINIMIAL TOE LAND PATTERN

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-UMLP10Arev6.



Figure 16. 10-Lead, Ultrathin Molded Leadless Package (UMLP)

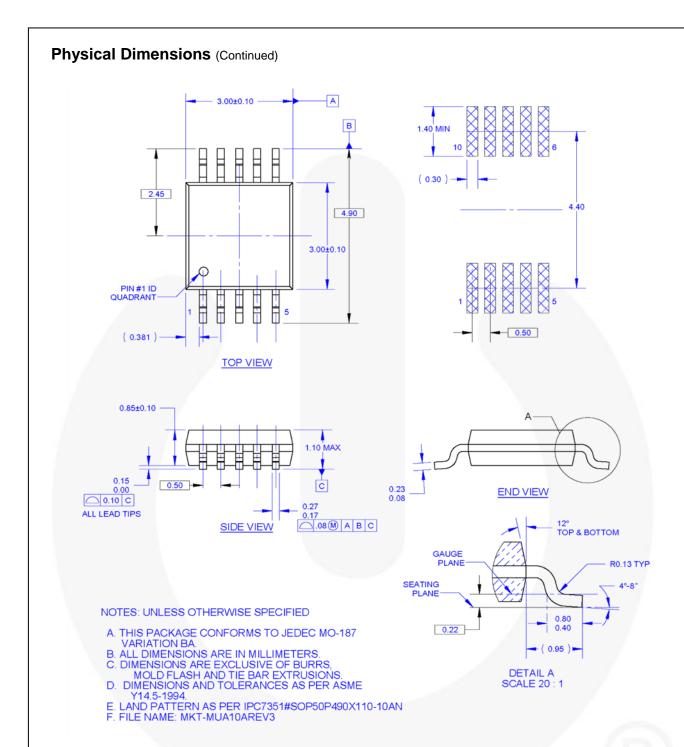


Figure 17. 10-Lead, Molded Small Outline Package (MSOP)





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